

ELECTRONICS & TELECOMMUNICATION ENGINEERING ELECTRONIC DEVICES & VLSI

Volume - 1 : Study Material with Classroom Practice Questions





Let us consider n-type semiconductor

$$R_{\rm H} = \frac{1}{nq}$$

$$n = \frac{1}{qR_{\rm H}}$$

$$= \frac{1}{1.6 \times 10^{-19} \times 3.6 \times 10^{-4}}$$

$$= 1.736 \times 10^{22} \text{ m}^{-3}$$

08. Ans: (b)

Sol: At equilibrium No. of e^- density = No. of hole density \therefore given e⁻ density is n(x₁) = 10 n(x₂) 12. \Rightarrow n(x₁) is majority \Rightarrow n(x₂) is minority $\therefore P(\mathbf{x}_2) = 10P(\mathbf{x}_1)$ 09. Ans: (b) **Sol:** $\rho_{p} = 3 \times 10^{3} \Omega - m$ $\mu_p = 0.12 \text{ m}^2/\text{V-sec}$ $V_{\rm H} = 60 {\rm mV}$ $\rho_{\rm p} = \frac{1}{\sigma_{\rm p}}$ Since $3 \times 10^3 = \frac{1}{p q \mu_p}$ $p = \frac{1}{3 \times 10^3 \times 1.6 \times 10^{-19} \times 0.12}$ $P = 1.736 \times 10^{16} \text{ m}^{-3}$ $R_{\rm H} = \frac{1}{pq}$ $=\frac{1}{1.736\times10^{16}\times1.6\times10^{-19}}$ $= 360 \text{ m}^{3}/\text{C}$ 10. Ans: (b)

Sol: $J_{drift} = n\mu_n qE + p\mu_P qE$ $J_{drift} = [(n.q)\mu_n + (p.q)\mu_p]E$ J_{drift} = $[\rho_n \mu_n + \rho_p \mu_p]$ J α ' ρ ' \downarrow Charge concentration **11.** Ans: (c) Sol: $D_n = 20 \text{ cm}^2/\text{s}$ $\mu_n = 1600 \text{ cm}^2/\text{V-s}$ $\frac{D}{\mu} = \frac{kT}{q} = V_T$ $\Rightarrow V_T = \frac{20}{1600} = 12.5 \text{ mV}$ **12.** Ans: (d) Sol: Conductivity of a semiconductor,

 $\sigma = (n\mu_n + p\mu_p)q$ Where, $\mu_n \rightarrow \text{mobility of electrons}$ $\mu_p \rightarrow \text{mobility of holes}$ $n \rightarrow \text{electron concentration}$ $p \rightarrow \text{hole concentration}$ $q \rightarrow \text{electron charge}$

13. Ans: (c)
Sol:
$$N_A = 2.29 \times 10^{16}$$

 $E_{Fi} - E_{Fp} = kT \ln\left(\frac{N_A}{n_i}\right)$
 $= 0.02586 \ln\left(\frac{2.29 \times 10^{16}}{1.5 \times 10^{10}}\right)$
 $= 0.3682 \text{ eV}$
 $\simeq 0.37 \text{ eV}$

14. Ans: (b) Sol: Given, 2 wires \therefore W₁ & W₂ d₂ = 2d₁ where d = diameter of wire L₂ = 4L₁ where L = length of wire

17. Ans: (a)

18. Ans: (a)

Sol: In intrinsic semiconductor, No. of $e^- = No.$ of holes

concentration decreases.

Relation between resistances of $W_1 \& W_2$

$$R = \frac{\rho L}{A} = \frac{\rho L}{\pi r^2} \qquad r = \frac{d}{2}$$

$$R = \frac{\rho L}{\pi \frac{d^2}{4}} = \frac{4\rho L}{\pi d^2} \qquad R \propto \frac{L}{d^2}$$

$$\frac{R_1}{R_2} = \frac{\frac{L_1}{d_1^2}}{\frac{L_2}{d_2^2}} = \frac{L_1}{d_1^2} \times \frac{d_2^2}{L_2} = \frac{L_1}{d_1^2} \times \frac{(2d_1)^2}{4L_1}$$

$$\Rightarrow \frac{R_1}{R_2} = 1 \qquad \therefore R_1 = R_2$$

15. Ans: (c)

Sol: Hall voltage, V_H is inversely proportional to carrier concentration

> $\Rightarrow \frac{V_{H2}}{V_{H1}} = \frac{P_1}{P_2} = \frac{P_1}{2P_1}$ $\therefore V_{H2} = \frac{1}{2} V_{H1}$

16. Ans: (b)

Sol: $\frac{D}{\mu} = \frac{kT}{q} = V_T$ $\therefore \mathbf{D} = \frac{0.36 \times 1.38 \times 10^{-23} \times 300}{1.6 \times 10^{-19}}$

true. electron mobility is 2 to 3 times more than hole mobility \Rightarrow true. Both the statements are true but statement II is not a

20. Ans: (a)

19. Ans: (b)

Sol: Both statement (I) and (II) are true and statement (II) is the correct explanation of statement (I).

correct explanation of statement I

Sol: In P-type, as doping increases hole concentration p increases. According to

Sol: In intrinsic semiconductor, electron hole

pairs are generated due to external energy \Rightarrow

mass action law $n_p = \frac{n_i^2}{p_p} \implies$ electron





∴ I =
$$\frac{5.5 - 0.498}{20}$$

= 0.2501 ⇒ 250 mA

- **08.** Ans: (a)
- **Sol:** Given $I_2^1 = I_1 \times 32$

Given
$$T_1 = 40^{\circ}C$$

 $I_2^1 = I_1 \left(2^{\frac{T_2 - T_1}{10}} \right)$
 $I_1 \times 32 = I_1 \left(2^{\frac{T_2 - T_1}{10}} \right)$
 $2^5 = 2^{\frac{T_2 - T_1}{10}}$

$$\Rightarrow \frac{T_2 - T_1}{10} = 5$$

$$T_2 - T_1 = 50$$

$$T_2 = 90^{\circ}C$$

$$T_2 = 50 + T_1$$

09. Ans: (b)

Sol: For either Si (or) Ge

$$\frac{\mathrm{dV}}{\mathrm{dT}} \cong -2.5 \ \mathrm{mV}/^{0}\mathrm{C}$$

 $T_2 = ?$

To maintain constant current

$$\frac{(V_2 - 700 \text{mV})}{(40 - 20)} \frac{\text{V}}{^{\circ}\text{C}} = -2.5 \times 10^{-3} \frac{\text{V}}{^{\circ}\text{C}}$$

$$\rightarrow V_2 = 650 \text{ mV} \approx 660 \text{ mV}$$

10. Ans: (b)

Sol: $C = \frac{\varepsilon_0 \varepsilon_r A}{d} \Rightarrow \frac{C}{A} = \frac{\varepsilon_0 \varepsilon_r}{d}$ = $\frac{11.7 \times 8.85 \times 10^{-12}}{10 \times 10^{-6}}$ = 10 µF

11. Ans: (d)

Sol: The cut-in voltage for Germanium diode is 0.3volt whereas the cut-in voltage for silicon diode is 0.7. So, cut-in voltage for silicon diode is greater than that for Germanium. Therefore, statement-I is false.

The reverse saturation current of Germanium diode is in the order of ' μ A' whereas that for silicon diode is 'nA'. So, Germanium diode has a higher reverse saturation current than silicon diode. Therefore, statement-II is true.

12. Ans: (b)

Sol: In all practical cases, the reverse saturation current (I₀) increased by 7% per °C rise in temperature. I₀ approximately doubles for every 10°C temperature rise for both Si and Ge materials. So, Statement-I is true.

In practical cases, $\frac{dV_0}{dT} = -2.5 \text{ mV/}^{\circ}\text{C}$ i.e., at

room temperature, the p-n junction voltage decreases by about 2.5 mV per °C with rise in temperature. So, statement-II is true but not the correct explanation of statement-I.

13. Ans: (c)

Sol:

OC

Since



The depletion region of an unbiased pnjunction contains negative ions in the p-side and positive ions in the n-side. So, an unbiased pn-junction develops a built-in potential at the junction with the n-side positive and the p-side negative. Therefore, statement-I is true.

The pn diode is a passive device. The pnjunction cannot behaves as a battery. Therefore statement-II is false.



06. Ans: (c)

Sol: Given circuit,



Ans: (a) 07.

Sol: The ideal characteristic of a stabilizer is constant output voltage with low internal resistance

08. Ans: (a)

Sol:

- In PN junction diode break down depends doping. doping on As increases breakdown voltage decreases.
- In Zener diode breakdown is less than 6 V
- It has Negative Temperature coefficient (operate in R. B)
- Avalanche diode breakdown greater than 6 V.

Ans: (b) 09.

Sol: Both statement (I) and (II) are true but statement (II) is not a correct explanation of statement (I) because DC voltage stabilizer circuit can be implemented by using other components like Op-Amp also. There is no need that only Zener diode to be used.

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Special Purpose Diodes

Chapter

01. Ans: (a)

Sol: Tunnel diode

It is highly doped S.C $(1:10^3)$

It is an abrupt junction (step) with both sides heavily doped made up of Ge (or) GaAs

It carries both majority and minority currents.

It can be used as oscillator

Operate in Negative Resistance region

Operate as fast switching device

02. Ans: (c)

Sol: The values of voltage (V_D) across a tunneldiode corresponding to peak and valley currents are V_P and V_V respectively. The range of tunnel-diode voltage V_D for which the slope of its I-V_D characteristics is negative would be $V_P \le V_D \le V_V$

03. Ans: (c)

Sol: Schottky diode is made of metal and semiconductor to decrease the switching times, hence it can be used for high frequency applications.

04. Ans: (a)

Sol:

	Symbol	Circuit	Applications			
		name				
	1	LED	Direct			
			Band gap			
		Tunnel	Fast			
		diode	Switching			
IG.			circuits			
		Varactor	Electronic			
		diode	Tuning			
	V/O					

05. Ans: (a)

Sol: The tunnel diode has a region in its voltage current characteristics where the current decreases with increased forward voltage known as its negative resistance region. This characteristic makes the tunnel diode useful in oscillators and as a microwave amplifier.

Bipolar Junction Transistor

- 01. Ans: (b) Sol: $\alpha = \beta/(1+\beta) = 0.9803$ $\alpha = \beta^* \gamma^*$ $\rightarrow \beta^* = 0.9803/0.995$ = 0.9852
- 02. Ans: (d)

Chapter

Sol: $I_C = 4mA$ $r_0 > 20k\Omega$

$$r_0 = \frac{V_A}{I_C}$$

- $$\label{eq:VA} \begin{split} \frac{V_A}{I_C} &> 20 k \Omega \\ V_A &> 20 k \Omega \times I_C \\ V_A &> 20 \times 10^3 \times 4 \times 10^{-3} \\ V_A &> 80 \end{split}$$
- 03. Ans: (d)
- Sol: $V_A = 100 V$ $I_C = 1 mA$ $V_{CE} = 10 V$ $I_{CQ} \left(1 + \frac{V_{CE}}{V_A} \right) = I_C$ If $V_A \rightarrow \infty \Rightarrow I_C = I_{CQ}$ $\Rightarrow I_C = I_{CQ} = \frac{1}{1 + \frac{10}{100}}$ = 0.909 mA
- 04. Ans: (b)
- **Sol:** The phenomenon is known as "Early Effect" in a bipolar transistor refers to a reduction of the effective base-width caused by the reverse biasing of the base-collector junction.

05. Ans: (a)

Sol: Given $\alpha = 0.995$, $I_E = 10mA$, $I_{co} = 0.5mA$ $I_{CEO} = (1 + \beta) I_{CBO}$ $I_{CEO} = \left(1 + \frac{\alpha}{1 - \alpha}\right) I_{CBO}$ $I_{CEO} = (1 + 199) \times 0.5 \times 10^{-6}$ $I_{CEO} = 100\mu A$

06. Ans: (b)

Sol: I_{CBO} is greater than I_{CO} . Reverse leakage current double for every Ten degrees rise in temperature.

07. Ans: (b)

Sol: Given base width $W_B = 50 \times 10^{-6}$ cm

Base doping N_B = 2×10¹⁶ cm⁻³

$$\in_{r} \in_{0} = \in \& \in = 10^{-12} \text{ F/cm}$$

$$V_{punch} = \frac{qN_{B}W_{B}^{2}}{2 \in}$$

$$= \frac{1.6 \times 10^{-19} \times 2 \times 10^{16} \times (50 \times 10^{-6})^{2}}{2 \times 10^{-12}}$$

$$V_{punch} = \frac{1.6 \times 2 \times 2500}{2} \times 10^{-3} = 4V$$

08. Ans: (a) Sol: $\alpha = 0.98$ $I_B = 40 \ \mu A$ $I_{CBO} = 1 \ \mu A$ $\beta = \frac{\alpha}{1-\alpha} = \frac{0.98}{1-0.98} = 49$ For a CE active BJT $I_C = \beta I_B + (1+\beta) I_{CBO}$ $= 49 \times 40 \times 10^{-6} + 50 \times 10^{-6}$ $= 2.01 \ \text{mA}$

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09. Ans: (b)

Sol:	$I_{CBO}=0.4~\mu A$
	$I_{CEO} = 60 \ \mu A$
	$I_{CEO} = (1+\beta) I_{CBO}$
	$1 + \beta = \frac{I_{CEO}}{I}$
	I _{CBO}
	$=\frac{60}{100}=150$
	0.4
	$\beta = 150 - 1$
	= 149
	$\alpha = \frac{\beta}{\beta}$
	$1 + \beta$
	$=\frac{149}{150}=0.993$
	130

10. Ans: (c)

Sol: Variation of base width due to reverse biased voltage across collector - base junction is known as "Early Effect".



As V_{CB} increases, effective base width (W'_B) decreases

11. Ans: (a)

Sol: Both statement (I) and (II) are true and statement (II) is the correct explanation of statement (I) At very high temperature, extrinsic

semiconductors will behave as intrinsic i.e., charge carriers will remains constant.

12. Ans: (b)

Sol:	Junction		Region of operation
	E - B	C - B	1
	F. B	F.B	Saturation Region
	F.B	R.B	Active Region
	R.B	F.B	Inverse active
	R.B	R.B	Region Cut-off Region

13. Ans: (c)

995

Sol: High power transistors are made of Si to withstand high temperature : Silicon is an indirect band gap material.

Chapter 6 Junction Field Effect Transistor



 $(V_{DS})_{min} = V_{GS} - V_P$ = -5 - (-8)= -5 + 8= 3 V08. Ans: (d) Sol: P. Voltage controlled device –FET (3) Q. Current controlled device -BJT (1)R. Conductivity modulation device--IMPATT diode (4)S. Negative conductance device -UJT (2)09. Ans: (d) **Sol:** $I_{DSS} = 12 \text{ mA}$ $V_{P} = -6 V$ Sol: $V_{GS} = 0 V$ $V_{DS} = 7 V$ At $V_{GS} = 0V$, $I_D = I_{DSS}$ = 12mA $:: I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_p} \right)$

V_{DS} at which pinch –off region means

10. Ans: (d)

Sol:

Device :	Application	
A. Diode	Rectifier (3)	Since
B. Transistor	Amplifier (1)	
C. Tunnel	Oscillator (2)	
diode		
D. Zener	Reference	
diode	Voltage (4)	

11. Ans: (a)
Sol:
$$g_{m0} = \left| \frac{2I_{DSS}}{V_p} \right| = \frac{2 \times 25 \times 10^{-3}}{10} = 5$$

12. Ans: (b)Sol: BJT is current controlled current source

 $(R_i = 0; R_o = \infty)$

 $Gain \times B.W$ is high

FET is voltage controlled current source

 $(\mathbf{R}_{i} = \infty; \mathbf{R}_{o} = 0)$

Gain \times B.W is low

UJT is a negative resistance device and can be used as an oscillator

UJT can be used as switch but can't be amplification

13. Ans: (a)

Sol: In FET majority carriers only exist.

In BJT majority & minority carriers exist.

$$G$$
 N – channel FET

Input resistance of FET is of the order of tens (or) hundreds of mega ohms (M Ω s)

: V_{gs} is reverse bias.

: In reverse bias very small leakage current $I_{\rm CO}$ flows through the gate.

15. Ans: (c)

Sol: FET's has high input impedance when compared to BJT. Because of this FET's are more suitable at the input stage of milli voltmeter and CRO's than BJT's. Generally FET has input impedance in the range of several M Ω

Statement (II) is false. So, option 'c' is correct

16. Ans: (d)

Sol: Statement (I) is false, because FET is a voltage control current source.

Statement (II) is true. Why because operation of FET does not depends on minority carrier i.e. FET operation depends on either electrons or holes as a majority carriers.

Optoelectronic Devices

Chapter



 $= 11.11\Omega$

03. Ans: (b)

Sol: Avalanche photo diodes are preferred over PIN diodes in optical communication because Avalanche photo diodes are (APDs), extracted from avalanche gain and excess noise measurement and higher sensitivity. PIN diodes generate more noise.

Ans: (c)

Sol: Photo diode always operates in reverse bias. When no light falls on photo diode, Small amount of reverse saturation current flows through the device called "dark current".

Ans: (a)

Sol: Give.

$$E_{g} = 1.12 \text{ eV},; \lambda_{1} = 1.1 \text{ } \mu\text{m}$$
$$\lambda_{2} = 0.87 \text{ } \mu\text{m}; E_{g2} =?$$
$$E_{g} = \frac{12400 \text{ A}^{0}}{\lambda} \Longrightarrow E_{g} \alpha \frac{1}{\lambda}$$
$$\frac{E_{g_{1}}}{E_{g_{2}}} = \frac{\lambda_{2}}{\lambda_{1}}$$

$$9 \Longrightarrow E_{g_2} = E_{g_1} \times \frac{\lambda_1}{\lambda_2} = 1.12 \times \frac{1.1}{0.87}$$
$$= 1.416 \text{ eV}$$

$$= 1.416 e$$

Ans: (a)

Sol: Sensitivity of photo diode depends on light intensity and depletion region width.

Ans: (d)

Sol:
$$I_D = \frac{24 - 1.8}{820} = 0.02707 \text{ A} = 27.07 \text{ mA}$$

Ans: (c)

Sol: Photo diode operate in R.B: Photo diode works on the principle of photo electric effect.



09. Ans: (b)

Sol: Voltage across PN junction diode resulting in current which in turn produce photons and light output. This inversion mechanism also called injection electro luminescence observed in LED's.

10. Ans: (b)

Sol: $\lambda = 890 \text{ A}^{\circ}$

$$\lambda = \frac{1.24 \times 10^{-6}}{E_{G}} m$$
$$= \frac{1.24 \times 10^{-6}}{890 \times 10^{-10}}$$

11. Ans: (d)

Sol: Solar cell converts optical (sunlight) energy into electrical energy.

12. Ans: (b)

Sol: R = 0.45 A/W

$$P_0 = 50 \ \mu W$$
$$R = \frac{I_p}{P_0}$$

 $I_{P} = R P_{0}$ = 0.45 × 50 = 22.5 µA Load current = I_P + I₀ = 22.5 µA + 1µA

 $= 23.5 \,\mu A$

13. Ans: (d)

Sol: LED: F.B Photo diode: R.B Zener diode: R.B Ordinary diode: F.B Tunnel diode: F.B Variable capacitance diode: R.B Avalanche diode: R.B

14. Ans: (c)

Sol: Tunnel diode is always operated in forward bias and light operated devices are operated in reverse bias. (Avalanche photo diode).

15. Ans: (b)

Sol: LED's and LASER's are used in forward bias.

Photo diodes are used in reverse bias.

16. Ans: (b)

Sol: Both statement (I) and (II) are true but statement (II) is not a correct explanation of statement (I).

17. Ans: (a)

Sol: Both statement (I) and (II) are true and statement (II) is the correct explanation of statement (I).

Since

MOSFET

Chapter

01. Ans: (c) Sol: $V_T = 1$ $V_{DS} = 5 - 1 = 4 V$ $V_{GS} = 3 - 1 = 2 V$ $V_{GS} - V_T = 2 - 1 = 1 V$ $V_{DS} > V_{GS} - V_T$ 4 > 1 → Saturation

02. Ans: (d)

Sol: In active region (or) saturation region, channel is pinched off. Number of carriers present in the channel decreases from source end to drain end due to potential increases from source to drain.

03. Ans: (d)

Sol:
$$\frac{I_{D_2}}{I_{D_1}} = \frac{K_n [V_{GS2} - V_T]^2}{K_n [V_{GS1} - V_T]^2}$$
$$\frac{I_{D_2}}{1 m A} = \frac{[1400 - 400]^2}{[900 - 400]^2}$$
$$I_{D_2} = 4 m A$$

04. Ans: (d)

Sol: $A = 1 \text{ sq } \mu m = 10^{-12} \text{ m}^2$ $d = 1 \ \mu m = 1 \times 10^{-6} \text{ m}$ $N_D = 10^{19}/\text{cm}^3$ $n_i = 10^{10}$ No. of holes = concentration × volume Volume = $A \times d = 10^{-18} \text{ m}$ $p = \frac{n_i^2}{n} = \frac{10^{20}}{10^{19}}$ = 10 holes / cm³ = 10 × 10⁶ holes / m³

: No. of holes = $10 \times 10^6 \times 10^{-18}$

 $= 10^{-11}$ holes ≈ 0

05. Ans: (b)

- Sol: 1) since it has n-type source & drain, it is n-channel MOSFET.
 - 2) Drain current flows only when $V_{GS} > 2V$, it implies it has threshold voltage (V_{th}) of +2V

 \Rightarrow It is enhancement type MOSFET.

4)
$$g_m = \mu_n C_{ox} \frac{W}{I} [V_{GS} - V_{Th}],$$

transconductance depends upon electron mobility.

06. Ans: (b)

2) 1

Sol:
$$C_{sbo} = \frac{\epsilon_{si} A}{d}$$

d = 10 nm

$$= 11.7 \times 8.9 \times 10^{-12} \, \text{F/m}$$

$$A = (0.2\mu \times 1\mu) + (0.2\mu \times 1\mu) + (0.2\mu \times 1\mu)$$

= 3(0.2\mu \times 1\mu) = 0.6 \times 10^{-12} m²
$$C_{sbo} = \frac{11.7 \times 8.9 \times 10^{-12} \times 0.6 \times 10^{-12}}{10 \times 10^{-9}}$$
$$C_{sbo} = 6.24 \times 10^{-15}$$

\approx 7 fF

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In practical IC, this cap will provided to
front and back sides also then area may be

$$A - (0.6 \times 10^{-12}) + (0.2\mu \times 1\mu) + (0.2\mu \times 1\mu)$$

$$A = 0.68 \times 10^{-12} m^2$$

$$C_{abs} = \frac{11.7 \times 8.9 \times 10^{-12} \times 0.68 \times 10^{-12}}{10 \times 10^{-2}} = 7fF$$
07. Ans: (a)
Sol: $L_{av} = \delta = 20 \text{ m}$

$$d = 10 \text{ nm}, w = 1 \mu \text{m}$$

$$e_{rai} = 11.7, e_{rox} = 3.9$$

$$e_0 = 8.9 \times 10^{-12} \text{ F/m}$$

$$C_{av} = C_{av} \text{ M} L_{av}$$

$$= \frac{6}{L_{av}} \frac{6}{w} \text{ w} L_{av}$$

$$= \frac{6}{L_{av}} \frac{6}{w} \text{ w} L_{av}$$

$$= \frac{6}{L_{av}} \frac{6}{w} \text{ w} L_{av}$$

$$= \frac{3.9 \times 8.9 \times 10^{-12} \text{ F/m}}{1 \times 10^{-2}}$$

$$= 0.69 \times 10^{-12} \text{ F/m}$$

$$C_0 = C_{av} \text{ M} L_{av}$$

$$= \frac{6}{L_{av}} \frac{6}{w} \text{ w} L_{av}$$

$$= \frac{3.9 \times 8.9 \times 10^{-12} \text{ F/m}}{1 \times 10^{-3}}$$

$$= 0.69 \times 10^{-12} \text{ F/m}$$

$$C_0 = 7 \text{ pF}$$

$$C_0 = C_{av} \text{ A} = \frac{6}{M} \frac{A}{L_{av}}$$

$$t_{as} = \frac{6}{W} \text{ A} = \frac{3.5 \times 10^{-13} \text{ F/em}}{7 \times 10^{-12}}$$

$$= 5 \times 10^{-6} \text{ cm} = 50 \text{ nm}$$
10. Ans: (b)
30.

$$t_{as} = \frac{6}{C_u} \text{ A} = \frac{3.5 \times 10^{-13} \text{ K/em}}{7 \times 10^{-12}}$$

$$= 5 \times 10^{-6} \text{ cm} = 50 \text{ nm}$$
10. Ans: (b)
30.

$$L_{av} = \frac{6}{C_u} \text{ A} = \frac{3.5 \times 10^{-13} \text{ K/em}}{7 \times 10^{-12}}}$$

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$$= 5 \times 10^{-6} \text{ cm} = 50 \text{ nm}$$
10. Ans: (b)
30.

$$L_{av} = \frac{7.75 - 2.5}{0.5} = 10.5 \text{ A}$$

$$L_{bv} = \frac{7.75 - 2.5}{0.5} = 9.5 \text{ A}$$



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12. Ans: (b)

Sol: The input impedance of insulated gate MOSFET is very high because of Sio₂ layer and revere bias at gate to source junction (i.e.at input junction)

> Statement (II) also true but not the correct explanation of statement (I)

13. Ans: (d)

Sol: Statement (I) is false, for same drain current rating n-channel MOSFET occupies less area than p-channel MOSFET why because electron mobility is higher than hole mobility

14. Ans: (a)

Sol: An Enhancement type MOSFET can be operate only in Enhancement mode. For nchannel EMOSFET, if V_{GS} (positive) > V_{th} , than only channel will formed between source and drain. So, for n-type EMOSFET only positive voltage can be applied to the gate with respec to the substrate. Therefore, statement-I is true.

Only with a positive voltage to the gate an "Inversion layer" is formed and conduction can take place. So statement-II is true and correct explanation of statement-I.

15. Ans: (b)

Sol: The drain current (I_D) of a MOSFET is controlled by the gate voltage. Therefore statement-I is true. The input impedance for a MOSFET is very and the current through the gate terminal (I_G) is zero. Therefore, MOSFET is an insulated gate FET. So statement-II is true but not the correct explanation for statement-I.













